The ornamental design for a printed circuit board standoff, as shown and described.

DESCRIPTION

FIG. 1 is a side, elevational view of my printed circuit board standoff; the opposite side comprising a mirror image thereof;

FIG. 2 is a front elevational view thereof, the rear view comprising a mirror image thereof;

FIG. 3 is a top plan view thereof; and;

FIG. 4 is a bottom plan view of my printed circuit board standoff.